

Features

- Colorless transparency lens type
- $\phi 5\text{mm}(\text{T}-1\frac{3}{4})$ all plastic mold type
- Low power consumption
- High radiant intensity

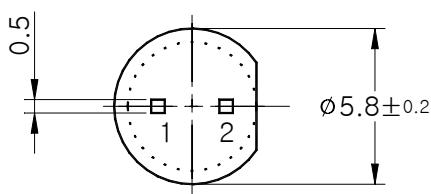
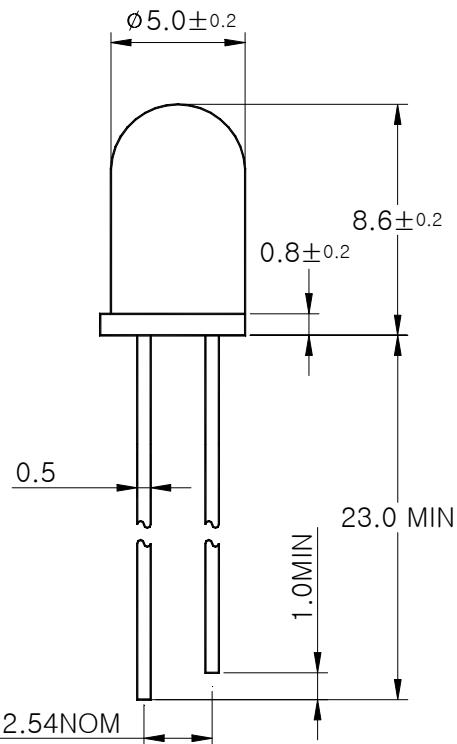
Applications

- Infrared remote control and free air transmission systems with low forward voltage and comfortable radiation angle requirements in combination with PIN photodiodes or phototransistors.

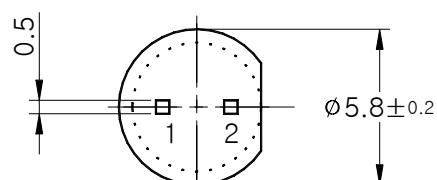
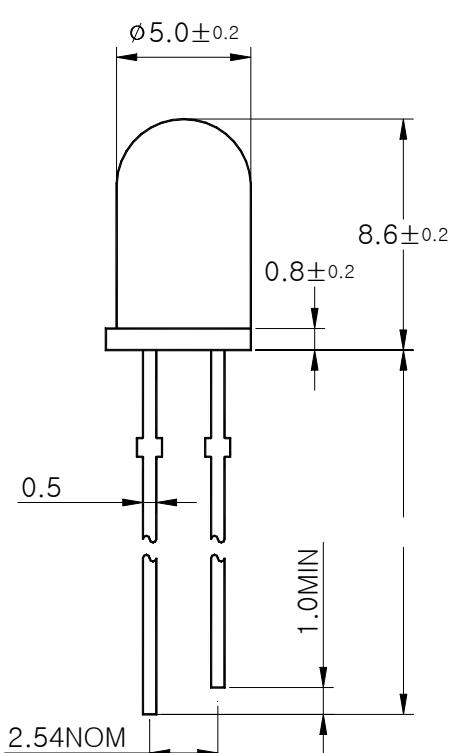
Outline Dimensions

unit : mm

STRAIGHT TYPE



STOPPER TYPE



PIN Connections

- 1.Anode
- 2.Cathode

Absolute maximum ratings

Characteristic	Symbol	Ratings	Unit
Power Dissipation	P _D	150	mW
Forward Current	I _F	100	mA
* ¹ Peak Forward Current	I _{FP}	1	A
Reverse Voltage	V _R	4	V
Operating Temperature	T _{opr}	-25~85	°C
Storage Temperature	T _{stg}	-30~100	°C
* ² Soldering Temperature	T _{sol}	260°C for 5 seconds	

*1.Duty ratio = 1/16, Pulse width = 0.1ms

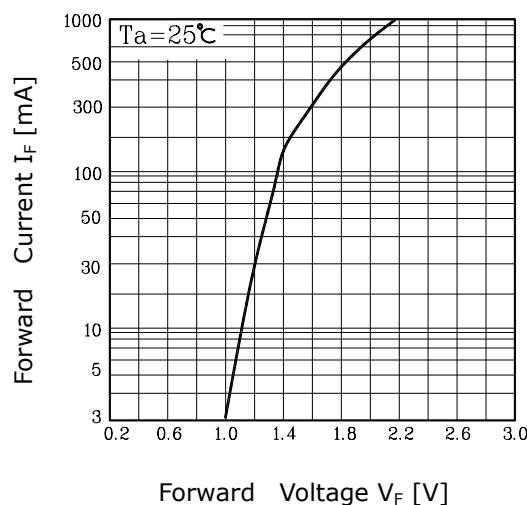
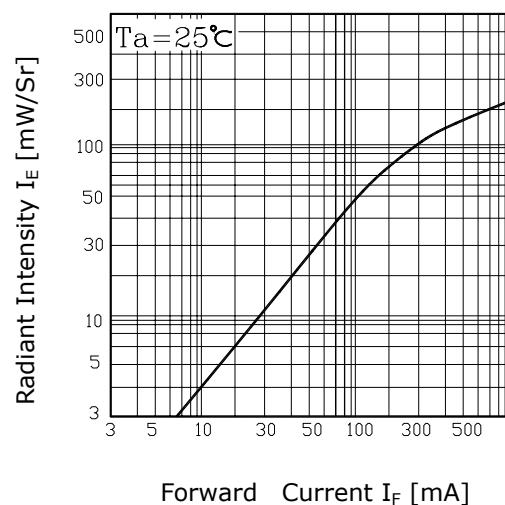
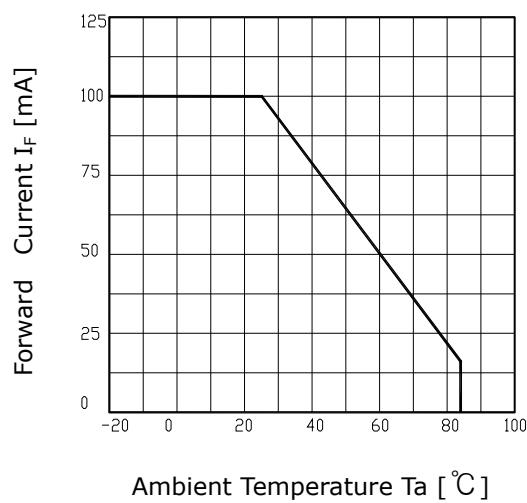
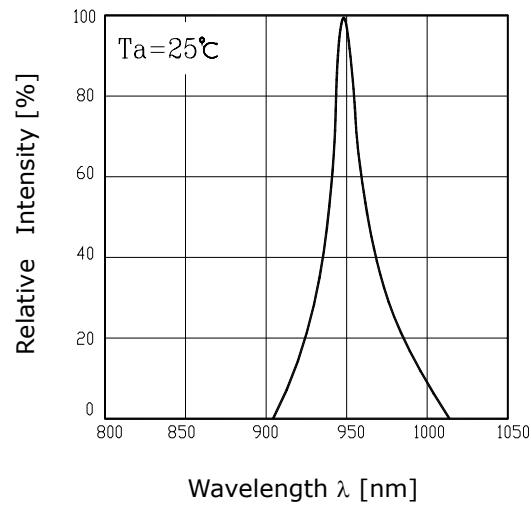
*2.Keep the distance more than 2.0mm from PCB to the bottom of IRED package

Electrical Characteristics

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	I _F = 50mA	-	1.3	1.7	V
Radiant Intensity	I _E	I _F = 50mA	25	50	-	mW/Sr
Peak Wavelength	λ _P	I _F = 50mA	-	950	-	nm
Spectrum Bandwidth	Δ λ	I _F = 50mA	-	50	-	nm
Reverse Current	I _R	V _R =4V	-	-	10	uA
* ³ Half angle	θ ^{1/2}	I _F = 50mA	-	±11	-	deg

*3. θ_{1/2} is the off-axis angle where the luminous intensity is 1/2 the peak intensity

Characteristic Diagrams

Fig. 1 I_F - V_F **Fig. 2** I_E - I_F **Fig. 3** I_F - T_a **Fig. 4 Spectrum Distribution****Fig. 5 Radiation Diagram**